TOSHIBA Field Effect Transistor Silicon N-Channel MOS Type (π -MOS VI)

2SK4108

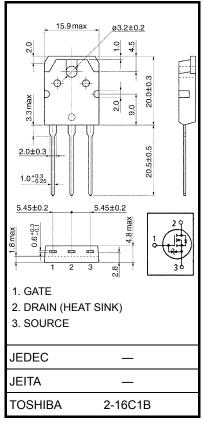
Switching Regulator Applications

Unit: mm

 $\begin{array}{ll} \bullet & \text{Low drain-source ON resistance} & : \text{RDS (ON)} = 0.\ 21\Omega\ (\text{typ.}) \\ \bullet & \text{High forward transfer admittance} & : |Y_{fs}| = 14\ \text{S (typ.}) \\ \bullet & \text{Low leakage current} & : \text{IDSS} = 100\ \mu\text{A (max)}\ (\text{VDS} = 500\ \text{V}) \\ \bullet & \text{Enhancement mode} & : \text{Vth} = 2.0 \text{\sim4.0 V (VDS} = 10\ \text{V, ID} = 1\ \text{mA}) \\ \end{array}$

Absolute Maximum Ratings (Ta = 25°C)

Characteristic		Symbol	Rating	Unit	
Drain-source voltage		V_{DSS}	500	V	
Drain-gate voltage (R _{GS} = 20 kΩ)		V_{DGR}	500	V	
Gate-source voltage		V_{GSS}	±30	V	
Drain current	DC (Note 1)	I _D	20	Α	
	Pulse (Note 1)	I _{DP}	80	Α	
Drain power dissipation (Tc = 25°C)		P_{D}	150	W	
Single-pulse avalanche energy (Note 2)		E _{AS}	960	mJ	
Avalanche current		I _{AR}	20	Α	
Repetitive avalanche energy (Note 3)		E _{AR}	15	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature range		T _{stg}	-55~150	°C	



Weight: 4.6 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature,

etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Thermal Characteristics

Characteristic	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	0.833	°C/W
Thermal resistance, channel to ambient	R _{th (ch-a)}	50	°C/W

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: V_{DD} = 90 V, T_{ch} = 25°C (initial), L = 4.08 mH, R_G = 25 Ω , I_{AR} = 20 A

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device. Handle with care.



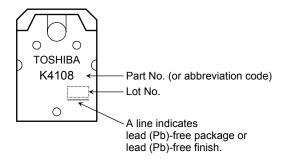
Electrical Characteristics (Ta = 25°C)

Chara	cteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	rrent	I _{GSS}	V _{GS} = ±25 V, V _{DS} = 0 V		_	±10	μA
Gate-source bre	eakdown voltage	V (BR) GSS	I _G = ±10 μA, V _{DS} = 0 V	±30	_	_	V
Drain cutoff curr	ent	I _{DSS}	V _{DS} = 500 V, V _{GS} = 0 V	_	_	100	μA
Drain-source br	eakdown voltage	V (BR) DSS	I _D = 10 mA, V _{GS} = 0 V	500	_	_	V
Gate threshold v	oltage	V_{th}	V _{DS} = 10 V, I _D = 1 mA	2.0	_	4.0	V
Drain-source Ol	N resistance	R _{DS} (ON)	V _{GS} = 10 V, I _D = 10 A	_	0.21	0.27	Ω
Forward transfer	admittance	Y _{fs}	V _{DS} = 10 V, I _D = 10 A	4.0	14	_	S
Input capacitano	е	C _{iss}			3400	_	pF
Reverse transfer capacitance		C _{rss}	V _{DS} = 25 V, V _{GS} = 0 V, f = 1 MHz	_	25	_	
Output capacitance		Coss			320	_	
Switching time	Rise time	t _r	V_{GS} $\stackrel{10}{0}$ $\stackrel{V}{\bigvee}$ $\stackrel{I_{D}}{\bigvee}$ $\stackrel{10}{\bigvee}$	_	70	_	
	Turn on time	t _{on}		_	130	_	
	Fall time	t _f		_	70	_	ns
	Turn off time	t _{off}		_	280	_	
Total gate charg plus gate-drain)		Qg			70		
Gate-source charge		Q _{gs}	$V_{DD} \approx 400 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 20 \text{ A}$		45	_	nC
Gate-drain ("Miller") charge		Q_{gd}			25	_	

Source-Drain Ratings and Characteristics (Ta = 25°C)

Characteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	_	_	_	20	Α
Pulse drain reverse current (Note 1)	I _{DRP}	_		_	80	Α
Forward voltage (diode)	V _{DSF}	I _{DR} = 20 A, V _{GS} = 0 V	_	_	-1.7	V
Reverse recovery time	t _{rr}	I _{DR} = 20 A, V _{GS} = 0 V		1300		ns
Reverse recovery charge	Q _{rr}	dl _{DR} / dt = 100 A / μs	-	20	_	μC

Marking



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